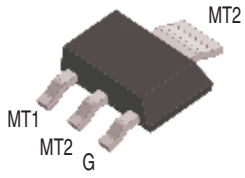
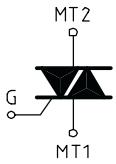
FAGOR

STANDARD TRIAC

SOT223
(Plastic)





On-State Current
1 Amp

Gate Trigger Current
≤ 25 mA

Off-State Voltage
200 V ÷ 800 V

This series of TRIACs uses a high performance PNPN technology.

These parts are intended for general purpose AC switching applications with highly inductive loads.

Absolute Maximum Ratings, according to IEC publication No. 134

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
$I_{T(RMS)}$	RMS On-state Current (full sine wave)	All Conduction Angle, T_C = 95 °C	1	A
I_{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	8.5	A
I_{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	8	A
I^2t	Fusing Current	t_p = 10 ms, Half Cycle	0.32	A^2s
I_{GM}	Peak Gate Current	20 µs max. T_j =125°C	1	A
$P_{G(AV)}$	Average Gate Power Dissipation	T_j =125°C	0.1	W
dI / dt	Critical rate of rise of on-state current	I_G = 2x I_{GT}, t_r ≤100ns f= 120 Hz, T_j =125°C	20	A/µs
T_j	Operating Temperature		(-40 +125)	°C
T_{stg}	Storage Temperature		(-40 +150)	°C
T_{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER	VOLTAGE					Unit
		B	D	M	S	N	
V_{DRM} V_{RRM}	Repetitive Peak Off State Voltage	200	400	600	700	800	V

Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	Quadrant		SENSITIVITY	Unit
					10	
I_{GT} (1)	Gate Trigger Current	V_D = 12 V_{DC} , R_L = 33Ω, T_j = 25 °C	Q1÷Q3 Q4	MAX MAX	25 25	mA mA
V_{GT}	Gate Trigger Voltage	V_D = 12 V_{DC} , R_L = 33Ω, T_j = 25 °C	Q1÷Q4	MAX	1.3	V
V_{GD}	Gate Non Trigger Voltage	V_D = V_{DRM} , R_L = 3.3KΩ, T_j = 125 °C	Q1÷Q4	MIN	0.2	V
I_H (2)	Holding Current	I_T = 50 mA , Gate open, T_j = 25 °C		MAX	25	mA
I_L	Latching Current	I_G = 1.2 I_{GT}, T_j = 25 °C	Q1,Q3,Q4 Q2	MAX MAX	25 50	mA
dV/dt (2)	Critical Rate of Voltage Rise	V_D = 0.67 x V_{DRM} , Gate open T_j = 125 °C		MIN	200	V/µs
(dV/dt)c(2)	Critical rise rate of Commutating off-state voltage	(dI/dt)c = 2.7 A/ms T_j = 125 °C		MIN	4.4	V/µs
V_{TM} (2)	On-state Voltage	I_T = 1.1 Amp, tp = 380 µs, T_j = 25 °C		MAX	1.95	V
$V_{t(o)}$ (2)	Threshold Voltage	T_j = 125 °C		MAX	0.95	V
r_d (2)	Dynamic Resistance	T_j = 125 °C		MAX	1000	mΩ
I_{DRM}/I_{RRM}	Off-State Leakage Current	V_D = V_{DRM} , T_j = 125 °C V_R = V_{RRM} , T_j = 25 °C		MAX MAX	0.5 5	mA µA
$R_{th(j-c)}$	Thermal Resistance Junction-Case	for AC 360° conduction angle			80	°C/W
$R_{th(j-a)}$	Thermal Resistance Junction- Ambient				60	°C/W

(1) Minimum I_{GT} is guaranted at 5% of I_{GT} max.

(2) For either polarity of electrode MT2 voltage with reference to electrode MT1.

PART NUMBER INFORMATION

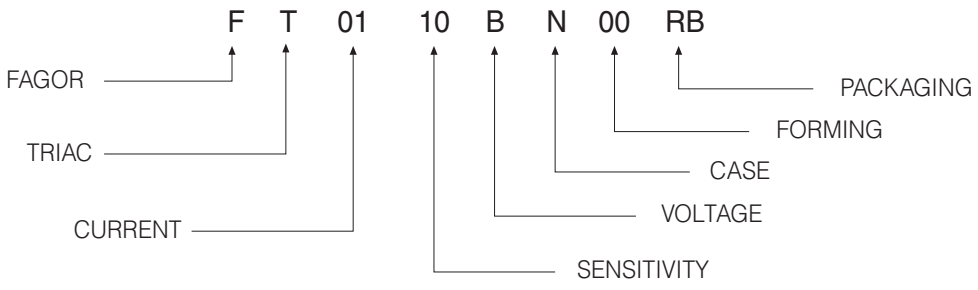


Fig. 1: Maximum power dissipation versus RMS on-state curren (full cycle).

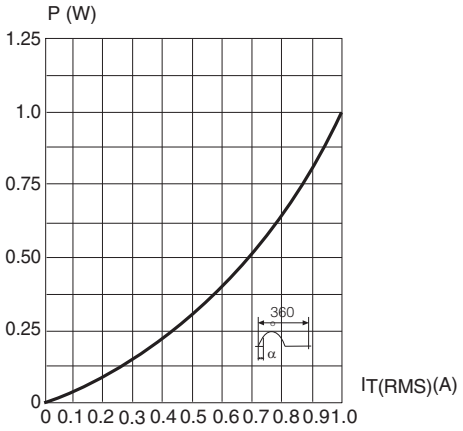


Fig. 2: RMS on-state current versus case temperature (full cycle).

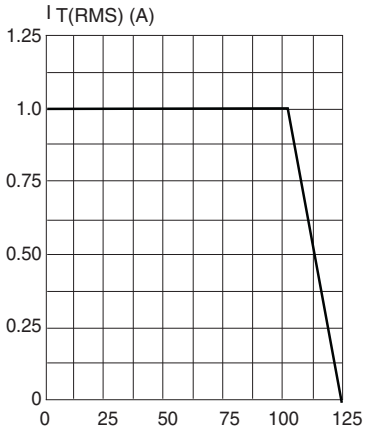


Fig. 3: : Relative variation of thermal impedance versus pulse duration.

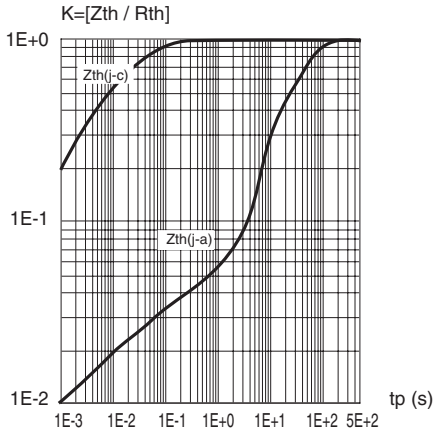


Fig. 4: On-state characteristics (maximum values)

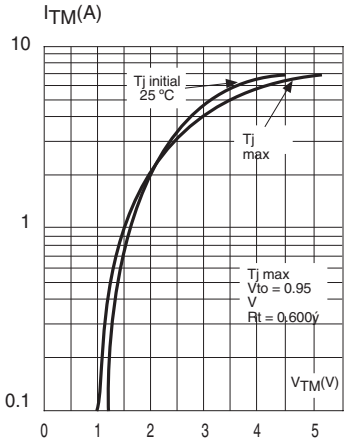


Fig. 5: Surge peak on-state current versus number of cycles

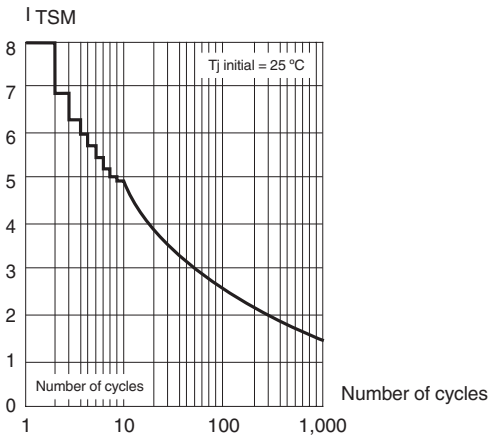


Fig. 6: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponding value of I^2t.

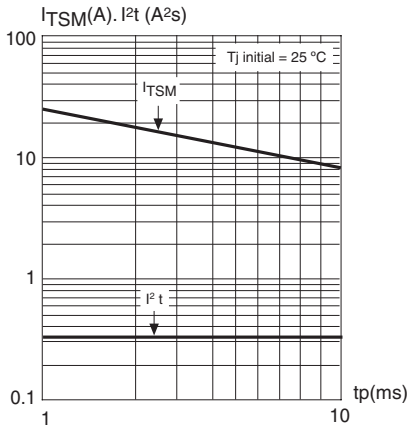


Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

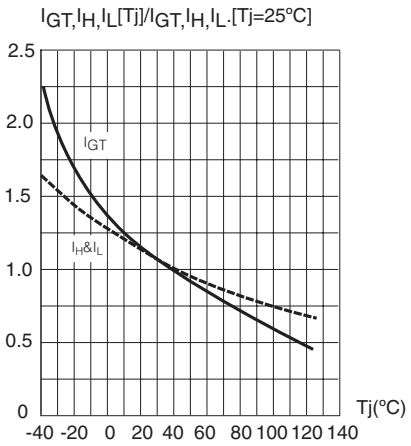


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature

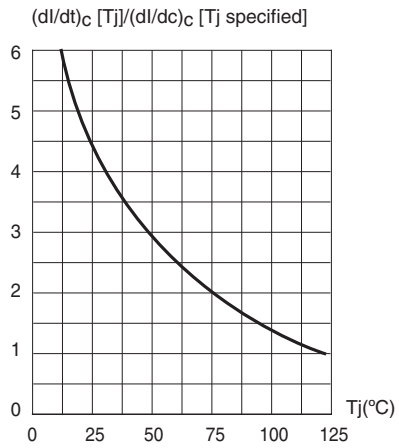
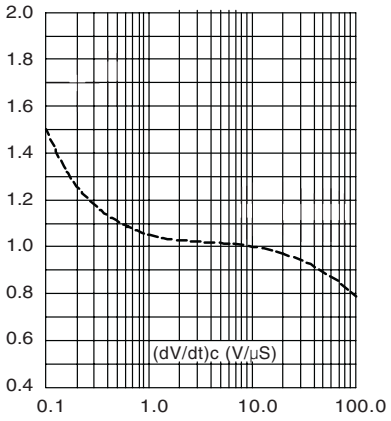


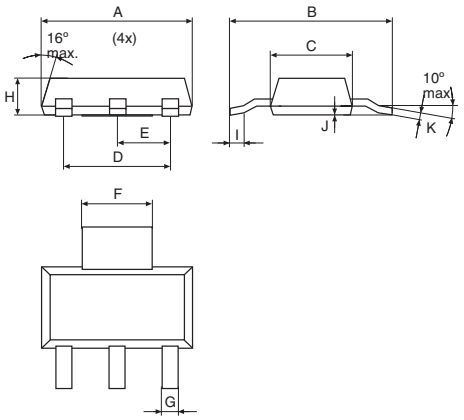
Fig. 9: Relative variation of critical rate of decrease of main current versus

(dV/dt)c (typical values).



PACKAGE MECHANICAL DATA

SOT223 (Plastic)



REF.	DIMENSIONS Milimeters		
	Min.	Typ.	Max.
A	6.30	6.50	6.70
B	6.70	7.00	7.30
C	3.30	3.50	3.70
D	-	4.60	-
E	-	2.30	-
F	2.95	3.00	3.15
G	0.65	0.70	0.85
H	1.50	1.60	1.70
I	0.50	0.60	0.70
J	-	0.02	0.05
K	0.25	0.30	0.35

Weight: 0.11 g

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